

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
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Application Number:	13405750														
CORRESPONDENCE DATA															
Fax Number:	(215)568-6499														
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CH \$40.00 13405750

ATTORNEY DOCKET NUMBER:	HITACHI2-21010198US01
NAME OF SUBMITTER:	Daniel N. Calder
Total Attachments: 2 source=21010198US01_Assignment_EFS#page1.tif source=21010198US01_Assignment_EFS#page2.tif	

ASSIGNMENT

Yosuke Ota, Yoshiro Hirose, Atsushi Sano, Osamu Kasahara, Kazuyuki Okuda, Kiyohiko Maeda, residing at Toyama, Japan, citizens of Japan (hereafter the undersigned); are the inventor of

Method of Manufacturing Semiconductor Device and Method of Processing Substrate and Substrate Processing Apparatus for which the undersigned executed an application for United States Letters Patent, U.S. Patent Application No. 13/405,750, filed February 27, 2012.

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Hitachi Kokusai Electric Inc., [a / an] company, having a principal place of business at

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan
(hereafter referred to as the assignee), is desirous of acquiring the entire right, title, and interest in said invention, all applications for, and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign, and transfer to the assignee and assignee's successors, assigns, and legal representatives the entire right, title, and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 15th day of March, 2012

at Tokyo, Japan.
(Place)

Witness:

Tosuke Ota (L.S.)
Yosuke Ota

Yoshiro Hirose (L.S.)
Yoshiro Hirose

Atsushi Sano (L.S.)
Atsushi Sano

Osamu Kasahara (L.S.)
Osamu Kasahara

Kazuyuki Okada (L.S.)
Kazuyuki Okada

Kiyohiko Maeda (L.S.)
Kiyohiko Maeda

(Although not mandatory, if possible,
please subscribe appropriate notarization and obtain APOSTILLE)